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Title of the Invention

METHOD OF MANUFACTURING MULTILAYER CIRCUIT BOARD



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BACKGROUND OF THE INVENTION

(1) Field of the Invention

The present invention relates to a method of manufacturing a multilayer circuit board.

(2) Description of Related Art

The build-up process is well known as a conventional method of manufacturing a multilayer circuit board. For example, a multilayer circuit board is manufactured as follows in this process. Firstly, via holes are formed at prescribed positions in a one-side copper-clad laminate manufactured by applying a copper foil to one side of an insulating substrate. The via holes are filled with an electrically conductive paste. A copper foil is bonded to the insulating substrate side of the one-side copper-clad laminate by pressing etched so that a prescribed conductor circuit is formed.

A printed board manufactured as described above serves as a core board. Insulating substrates are stacked on both sides of the core board respectively and bonded by pressing. Thereafter, via holes are formed at prescribed positions and then filled with the conductive paste. After copper foils are stacked on both sides of the board and pressed again, prescribed conductor circuits are formed on each copper foil. This step is repeated to further increase the number of layers so that a multilayer circuit board is manufactured.

In the foregoing method, the printed board serving as the core board is manufactured and circuit patterns are sequentially stacked on the core board. Accordingly, since the